

Qing-An Huang

List of Publications by Citations

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227
papers

2,933
citations

28
h-index

46
g-index

269
ext. papers

3,620
ext. citations

3.2
avg, IF

5.44
L-index

| # | Paper | IF | Citations |
|-----|---|------|-----------|
| 227 | Analysis and design of polysilicon thermal flexure actuator. <i>Journal of Micromechanics and Microengineering</i> , 1999 , 9, 64-70 | 2 | 260 |
| 226 | Metal oxide semiconductor nanomembrane-based soft unnoticeable multifunctional electronics for wearable human-machine interfaces. <i>Science Advances</i> , 2019 , 5, eaav9653 | 14.3 | 136 |
| 225 | LC Passive Wireless Sensors Toward a Wireless Sensing Platform: Status, Prospects, and Challenges. <i>Journal of Microelectromechanical Systems</i> , 2016 , 25, 822-841 | 2.5 | 123 |
| 224 | A novel capacitive-type humidity sensor using CMOS fabrication technology. <i>Sensors and Actuators B: Chemical</i> , 2004 , 99, 491-498 | 8.5 | 111 |
| 223 | A modified cellular automata algorithm for the simulation of boundary advancement in deposition topography simulation. <i>Journal of Micromechanics and Microengineering</i> , 2006 , 16, 1-8 | 2 | 106 |
| 222 | A novel capacitive pressure sensor based on sandwich structures. <i>Journal of Microelectromechanical Systems</i> , 2005 , 14, 1272-1282 | 2.5 | 70 |
| 221 | 2-D Micromachined Thermal Wind Sensors—A Review. <i>IEEE Internet of Things Journal</i> , 2014 , 1, 216-232 | 10.7 | 64 |
| 220 | . <i>Journal of Microelectromechanical Systems</i> , 2015 , 24, 575-581 | 2.5 | 57 |
| 219 | . <i>Journal of Microelectromechanical Systems</i> , 2015 , 24, 1117-1123 | 2.5 | 54 |
| 218 | Improvement of the 2D dynamic CA method for photoresist etching simulation and its application to deep UV lithography simulations of SU-8 photoresists. <i>Journal of Micromechanics and Microengineering</i> , 2007 , 17, 2538-2547 | 2 | 52 |
| 217 | High-Voltage Flexible Microsupercapacitors Based on Laser-Induced Graphene. <i>ACS Applied Materials & Interfaces</i> , 2018 , 10, 26357-26364 | 9.5 | 49 |
| 216 | A Fully Packaged CMOS Interdigital Capacitive Humidity Sensor With Polysilicon Heaters. <i>IEEE Sensors Journal</i> , 2011 , 11, 2986-2992 | 4 | 49 |
| 215 | Fabrication of a Micromachined Two-Dimensional Wind Sensor by Au/Au Wafer Bonding Technology. <i>Journal of Microelectromechanical Systems</i> , 2012 , 21, 467-475 | 2.5 | 47 |
| 214 | An analytical model for pull-in voltage of clamped-clamped multilayer beams. <i>Sensors and Actuators A: Physical</i> , 2004 , 116, 15-21 | 3.9 | 47 |
| 213 | A silicon directly bonded capacitive absolute pressure sensor. <i>Sensors and Actuators A: Physical</i> , 2007 , 135, 507-514 | 3.9 | 42 |
| 212 | A Micromachined Inline-Type Wideband Microwave Power Sensor Based on GaAs MMIC Technology. <i>Journal of Microelectromechanical Systems</i> , 2009 , 18, 705-714 | 2.5 | 41 |
| 211 | Analytical modeling and optimization for a laterally-driven polysilicon thermal actuator. <i>Microsystem Technologies</i> , 1999 , 5, 133-137 | 1.7 | 40 |

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| 210 | Size and temperature dependence of Young's modulus of a silicon nano-plate. <i>Journal Physics D: Applied Physics</i> , 2008 , 41, 165406 | 3 | 38 |
| 209 | . <i>Journal of Microelectromechanical Systems</i> , 2005 , 14, 464-471 | 2.5 | 38 |
| 208 | Extending the remote distance of LC passive wireless sensors via strongly coupled magnetic resonances. <i>Journal of Micromechanics and Microengineering</i> , 2014 , 24, 125021 | 2 | 36 |
| 207 | A cellular automaton-based simulator for silicon anisotropic etching processes considering high index planes. <i>Journal of Micromechanics and Microengineering</i> , 2007 , 17, S38-S49 | 2 | 36 |
| 206 | LC Wireless Sensitive Pressure Sensors With Microstructured PDMS Dielectric Layers for Wound Monitoring. <i>IEEE Sensors Journal</i> , 2018 , 18, 4886-4892 | 4 | 35 |
| 205 | A Cross-Type Thermal Wind Sensor With Self-Testing Function. <i>IEEE Sensors Journal</i> , 2010 , 10, 340-346 | 4 | 33 |
| 204 | Modeling, design and fabrication of a triple-layered capacitive pressure sensor. <i>Sensors and Actuators A: Physical</i> , 2005 , 117, 71-81 | 3.9 | 32 |
| 203 | . <i>Journal of Microelectromechanical Systems</i> , 2017 , 26, 1073-1081 | 2.5 | 31 |
| 202 | Passive wireless integrated humidity sensor based on dual-layer spiral inductors. <i>Electronics Letters</i> , 2014 , 50, 1287-1289 | 1.1 | 30 |
| 201 | Flip-Chip Packaging for a Two-Dimensional Thermal Flow Sensor Using a Copper Pillar Bump Technology. <i>IEEE Sensors Journal</i> , 2007 , 7, 990-995 | 4 | 30 |
| 200 | Implementation of Multiparameter Monitoring by an LC-Type Passive Wireless Sensor Through Specific Winding Stacked Inductors. <i>IEEE Internet of Things Journal</i> , 2015 , 2, 168-174 | 10.7 | 29 |
| 199 | Macro-modeling for polysilicon cascaded bent beam electrothermal microactuators. <i>Sensors and Actuators A: Physical</i> , 2006 , 128, 165-175 | 3.9 | 27 |
| 198 | Numerical simulation of a polysilicon thermal flexure actuator. <i>Microsystem Technologies</i> , 2002 , 8, 17-21 | 1.7 | 27 |
| 197 | A Passive Wireless Adaptive Repeater for Enhancing the Readout of LC Passive Wireless Sensors. <i>IEEE Microwave and Wireless Components Letters</i> , 2016 , 26, 543-545 | 2.6 | 26 |
| 196 | A Novel Three-State RF MEMS Switch for Ultrabroadband (DC-40 GHz) Applications. <i>IEEE Electron Device Letters</i> , 2013 , 34, 1062-1064 | 4.4 | 26 |
| 195 | A FCOB packaged thermal wind sensor with compensation. <i>Microsystem Technologies</i> , 2010 , 16, 511-518 | 1.7 | 24 |
| 194 | A microwave power sensor based on GaAs MMIC technology. <i>Journal of Micromechanics and Microengineering</i> , 2007 , 17, 2132-2137 | 2 | 23 |
| 193 | Low Cost Paper-Based LC Wireless Humidity Sensors and Distance-Insensitive Readout System. <i>IEEE Sensors Journal</i> , 2019 , 19, 4717-4725 | 4 | 22 |

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| 192 | Development of a self-packaged 2D MEMS thermal wind sensor for low power applications. <i>Journal of Micromechanics and Microengineering</i> , 2015 , 25, 085011 | 2 | 21 |
| 191 | Enhanced performance of a CMOS interdigital capacitive humidity sensor by graphene oxide 2011 , | | 21 |
| 190 | . <i>Journal of Microelectromechanical Systems</i> , 2009 , 18, 274-286 | 2.5 | 21 |
| 189 | Modeling, simulation and experimental verification of inclined UV lithography for SU-8 negative thick photoresists. <i>Journal of Micromechanics and Microengineering</i> , 2008 , 18, 125017 | 2 | 20 |
| 188 | A simple approach to characterizing the driving force of polysilicon laterally driven thermal microactuators. <i>Sensors and Actuators A: Physical</i> , 2000 , 80, 267-272 | 3.9 | 20 |
| 187 | A monolithic integrated ultra-flexible all-solid-state supercapacitor based on a polyaniline conducting polymer. <i>Journal of Materials Chemistry A</i> , 2019 , 7, 15378-15386 | 13 | 19 |
| 186 | Sensitivity Improvement of a 2D MEMS Thermal Wind Sensor for Low-Power Applications. <i>IEEE Sensors Journal</i> , 2016 , 16, 4300-4308 | 4 | 19 |
| 185 | Micromachining of Pyrex 7740 Glass by Silicon Molding and Vacuum Anodic Bonding. <i>Journal of Microelectromechanical Systems</i> , 2011 , 20, 909-915 | 2.5 | 18 |
| 184 | Young's modulus of silicon nanoplates at finite temperature. <i>Applied Surface Science</i> , 2008 , 255, 2449-2455 | 4.5 | 18 |
| 183 | A physical model for silicon anisotropic chemical etching. <i>Semiconductor Science and Technology</i> , 2005 , 20, 524-531 | 1.8 | 18 |
| 182 | Novel DC-40 GHz MEMS series-shunt switch for high isolation and high power applications. <i>Sensors and Actuators A: Physical</i> , 2014 , 214, 101-110 | 3.9 | 17 |
| 181 | Modeling and Simulations of Anisotropic Etching of Silicon in Alkaline Solutions with Experimental Verification. <i>Journal of the Electrochemical Society</i> , 2009 , 156, F29 | 3.9 | 17 |
| 180 | Pull-in characterization of doubly-clamped composite beams. <i>Sensors and Actuators A: Physical</i> , 2009 , 151, 118-126 | 3.9 | 17 |
| 179 | The influence of surface effects on size-dependent mechanical properties of silicon nanobeams at finite temperature. <i>Journal Physics D: Applied Physics</i> , 2009 , 42, 045409 | 3 | 17 |
| 178 | Lateral Contact Three-State RF MEMS Switch for Ground Wireless Communication by Actuating Rhombic Structures. <i>Journal of Microelectromechanical Systems</i> , 2013 , 22, 10-12 | 2.5 | 16 |
| 177 | A novel 2D dynamic cellular automata model for photoresist etching process simulation. <i>Journal of Micromechanics and Microengineering</i> , 2005 , 15, 652-662 | 2 | 16 |
| 176 | Gamma and electron beam irradiation effects on the resistance of micromachined polycrystalline silicon beams. <i>Sensors and Actuators A: Physical</i> , 2012 , 177, 99-104 | 3.9 | 15 |
| 175 | Effect of Environmental Humidity on Dielectric Charging Effect in RF MEMS Capacitive Switches Based on Si_3N_4 Properties. <i>Journal of Microelectromechanical Systems</i> , 2013 , 22, 637-645 | 2.5 | 15 |

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| 174 | Field emission from surface states of silicon. <i>Journal of Applied Physics</i> , 1997 , 81, 7589-7594 | 2.5 | 15 |
| 173 | A Novel 3-D Dynamic Cellular Automata Model for Photoresist-Etching Process Simulation. <i>IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems</i> , 2007 , 26, 100-114 | 2.5 | 15 |
| 172 | Field emission from the surface quantum well of silicon. <i>Applied Surface Science</i> , 1996 , 93, 77-83 | 6.7 | 15 |
| 171 | A nodal analysis method for simulating the behavior of electrothermal microactuators. <i>Microsystem Technologies</i> , 2007 , 14, 119-129 | 1.7 | 14 |
| 170 | Effect of native oxides on the elasticity of a silicon nano-scale beam. <i>Solid State Communications</i> , 2008 , 145, 351-354 | 1.6 | 14 |
| 169 | Octagon-Shaped 2-D Micromachined Thermal Wind Sensor for High-Accurate Applications. <i>Journal of Microelectromechanical Systems</i> , 2018 , 27, 739-747 | 2.5 | 14 |
| 168 | . <i>Journal of Microelectromechanical Systems</i> , 2015 , 24, 2033-2039 | 2.5 | 13 |
| 167 | A micromachined silicon capacitive temperature sensor for wide temperature range applications. <i>Journal of Micromechanics and Microengineering</i> , 2010 , 20, 055036 | 2 | 13 |
| 166 | Instability of field emission from silicon covered with a thin oxide due to electron trapping. <i>Journal of Applied Physics</i> , 1996 , 79, 3703-3707 | 2.5 | 13 |
| 165 | A 2D Wind Sensor Using the ΔP Thermal Feedback Control. <i>Journal of Microelectromechanical Systems</i> , 2018 , 27, 377-379 | 2.5 | 12 |
| 164 | An online test microstructure for thermal conductivity of surface-micromachined polysilicon thin films. <i>IEEE Sensors Journal</i> , 2006 , 6, 428-433 | 4 | 12 |
| 163 | An LC Passive Wireless Multifunctional Sensor Using a Relay Switch. <i>IEEE Sensors Journal</i> , 2016 , 16, 4968-4973 | 4 | 12 |
| 162 | . <i>IEEE Transactions on Circuits and Systems I: Regular Papers</i> , 2016 , 63, 1426-1433 | 3.9 | 10 |
| 161 | A system-level model for a silicon thermal flow sensor. <i>Microsystem Technologies</i> , 2009 , 15, 279-285 | 1.7 | 10 |
| 160 | Influence of environmental temperature on the dynamic properties of a die attached MEMS device. <i>Microsystem Technologies</i> , 2009 , 15, 925-932 | 1.7 | 10 |
| 159 | Gamma Irradiation Effects on Surface-Micromachined Polysilicon Resonators. <i>Journal of Microelectromechanical Systems</i> , 2011 , 20, 1071-1073 | 2.5 | 10 |
| 158 | Measurement of residual stress in multilayered thin films by a full-field optical method. <i>Sensors and Actuators A: Physical</i> , 2006 , 126, 93-97 | 3.9 | 10 |
| 157 | Experiment of the MEMS Wind Sensor Based on Temperature-Balanced Mode. <i>IEEE Sensors Journal</i> , 2017 , 17, 2316-2317 | 4 | 9 |

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| 156 | Effect of Insulation Trenches on Micromachined Silicon Thermal Wind Sensors. <i>IEEE Sensors Journal</i> , 2017 , 17, 8324-8331 | 4 | 9 |
| 155 | Humidity sensing properties of the sensor based on graphene oxide films with different dispersion concentrations 2011 , | | 9 |
| 154 | Orientation Effects in Ballistic High-Strained P-type Si Nanowire FETs. <i>Sensors</i> , 2009 , 9, 2746-59 | 3.8 | 9 |
| 153 | Modelling of the elastic properties of crystalline silicon using lattice dynamics. <i>Journal Physics D: Applied Physics</i> , 2011 , 44, 335401 | 3 | 9 |
| 152 | A field-enhanced generation model for field emission from p-type silicon. <i>IEEE Electron Device Letters</i> , 1997 , 18, 616-618 | 4.4 | 9 |
| 151 | A simple method for measuring the thermal diffusivity of surface-micromachined polysilicon thin films. <i>Journal of Micromechanics and Microengineering</i> , 2006 , 16, 981-985 | 2 | 9 |
| 150 | Field emission from a silicon surface potential well through a thin oxide. <i>Journal of Applied Physics</i> , 1995 , 78, 6770-6774 | 2.5 | 9 |
| 149 | Experimental Study of the Bending Effect on LC Wireless Humidity Sensors Fabricated on Flexible PET Substrates. <i>Journal of Microelectromechanical Systems</i> , 2018 , 27, 761-763 | 2.5 | 8 |
| 148 | A simple method for extracting material parameters of multilayered MEMS structures using resonance frequency measurements. <i>Journal of Micromechanics and Microengineering</i> , 2014 , 24, 075014 ² | | 8 |
| 147 | An Efficient Simulation System for Inclined UV Lithography Processes of Thick SU-8 Photoresists. <i>IEEE Transactions on Semiconductor Manufacturing</i> , 2011 , 24, 294-303 | 2.6 | 8 |
| 146 | Large-signal lumped-parameter macromodels for the equivalent circuit representation of electromechanical transducers. <i>Journal of Micromechanics and Microengineering</i> , 2004 , 14, 452-461 | 2 | 8 |
| 145 | Symmetric LC Circuit Configurations for Passive Wireless Multifunctional Sensors. <i>Journal of Microelectromechanical Systems</i> , 2019 , 28, 344-350 | 2.5 | 7 |
| 144 | Laterally-actuated inside-driven RF MEMS switches fabricated by a SOG process. <i>Journal of Micromechanics and Microengineering</i> , 2015 , 25, 065007 | 2 | 7 |
| 143 | Effects of Ambient Humidity on a Micromachined Silicon Thermal Wind Sensor. <i>Journal of Microelectromechanical Systems</i> , 2014 , 23, 253-255 | 2.5 | 7 |
| 142 | A Simple Extraction Method of Young's Modulus for Multilayer Films in MEMS Applications. <i>Micromachines</i> , 2017 , 8, | 3.3 | 7 |
| 141 | A hot film wind sensor with four Constant Temperature Difference elements fabricated on ceramic substrate 2011 , | | 7 |
| 140 | A nodal analysis method for electromechanical behavior simulation of bow-tie shaped microbeams. <i>Microsystem Technologies</i> , 2009 , 15, 985-991 | 1.7 | 7 |
| 139 | Modeling of H ₂ O adsorption-induced curvature of a metal/silicon nanocantilever. <i>Applied Surface Science</i> , 2009 , 255, 9404-9408 | 6.7 | 7 |

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| 138 | Analysis of electromagnetic interference of a capacitive RF MEMS switch during switching. <i>Microsystem Technologies</i> , 2008 , 14, 349-360 | 1.7 | 7 |
| 137 | Configuration of a Self-Heated Double Wheatstone Bridge for 2-D Wind Sensors. <i>Journal of Microelectromechanical Systems</i> , 2019 , 28, 125-130 | 2.5 | 7 |
| 136 | Comprehensive Simulations for Ultraviolet Lithography Process of Thick SU-8 Photoresist. <i>Micromachines</i> , 2018 , 9, | 3.3 | 7 |
| 135 | Parallelized Wireless Sensing System for Continuous Monitoring of Microtissue Spheroids. <i>ACS Sensors</i> , 2020 , 5, 2036-2043 | 9.2 | 6 |
| 134 | Effects of Metal Plane in LC Passive Wireless Sensors 2018 , 2, 1-3 | | 6 |
| 133 | Applying Metamaterial-Based Repeater in LC Passive Wireless Sensors to Enhance Readout. <i>IEEE Sensors Journal</i> , 2018 , 18, 1755-1760 | 4 | 6 |
| 132 | Design of LC-type passive wireless multi-parameter sensor 2013 , | | 6 |
| 131 | Temperature Effects on the Wind Direction Measurement of 2D Solid Thermal Wind Sensors. <i>Sensors</i> , 2015 , 15, 29871-81 | 3.8 | 6 |
| 130 | Fullerene as electrical hinge. <i>Applied Physics Letters</i> , 2012 , 100, 193111 | 3.4 | 6 |
| 129 | Field emission from a silicon surface-potential well based on an Airy function approach. <i>Journal of Applied Physics</i> , 1995 , 78, 1254-1258 | 2.5 | 6 |
| 128 | A robust and low-power 2-D thermal wind sensor based on a glass-in-silicon reflow process. <i>Microsystem Technologies</i> , 2016 , 22, 151-162 | 1.7 | 5 |
| 127 | Novel Anemometer Based on Inductor Bending Effect. <i>Journal of Microelectromechanical Systems</i> , 2019 , 28, 321-323 | 2.5 | 5 |
| 126 | In-situ determination of the coefficient of thermal expansion of polysilicon thin films using micro-rotating structures. <i>Thin Solid Films</i> , 2014 , 552, 184-191 | 2.2 | 5 |
| 125 | Micromachining of Pyrex7740 glass and their applications to wafer-level hermetic packaging of MEMS devices 2010 , | | 5 |
| 124 | A MEMS pressure sensor based on Hall effect 2011 , | | 5 |
| 123 | Field emission from silicon including continuum energy and surface quantization. <i>Applied Surface Science</i> , 1997 , 119, 229-236 | 6.7 | 5 |
| 122 | In-line method for extracting the temperature coefficient of resistance of surface-micromachined polysilicon thin films. <i>Sensors and Actuators A: Physical</i> , 2007 , 136, 249-254 | 3.9 | 5 |
| 121 | A new micro-rotating structure. <i>Journal of Physics: Conference Series</i> , 2006 , 34, 552-557 | 0.3 | 5 |

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| 120 | Design and finite element analysis of weighted-stiffness microelectromechanical digital-to-analogue converters. <i>Electronics Letters</i> , 2001 , 37, 755 | 1.1 | 5 |
| 119 | A New Interpretation of the Orientation Effect in GaAs Metal Semiconductor Field Effect Transistors. <i>Japanese Journal of Applied Physics</i> , 1991 , 30, L11-L14 | 1.4 | 5 |
| 118 | Three-Dimensional Simulation of DRIE Process Based on the Narrow Band Level Set and Monte Carlo Method. <i>Micromachines</i> , 2018 , 9, | 3.3 | 5 |
| 117 | DRIE trenches and full-bridges design for sensitivity improvement of MEMS silicon thermal wind sensor 2017 , | | 4 |
| 116 | Ceramic Film Packaging for 2-D Thermal Wind Sensor Using LTCC Technology. <i>Journal of Microelectromechanical Systems</i> , 2019 , 28, 1080-1087 | 2.5 | 4 |
| 115 | Temperature Effect and Its Compensation of a Micromachined 2-D Anemometer. <i>IEEE Sensors Journal</i> , 2019 , 19, 5454-5459 | 4 | 4 |
| 114 | Enhancing the Remote Distance of LC Passive Wireless Sensors by Parity-Time Symmetry Breaking. <i>Physical Review Applied</i> , 2020 , 13, | 4.3 | 4 |
| 113 | An Impedance Matching Method for LC Passive Wireless Sensors. <i>IEEE Sensors Journal</i> , 2020 , 20, 13833-13841 | 4.3 | 4 |
| 112 | A Generalized Polynomial Chaos-Based Approach to Analyze the Impacts of Process Deviations on MEMS Beams. <i>Sensors</i> , 2017 , 17, | 3.8 | 4 |
| 111 | A New Method for Real-Time Measuring the Temperature-Dependent Dielectric Constant of the Silicone Oil. <i>IEEE Sensors Journal</i> , 2016 , 16, 8792-8797 | 4 | 4 |
| 110 | Temperature Effects of a Ceramic MEMS Thermal Wind Sensor Based on a Temperature-Balanced Mode. <i>IEEE Sensors Journal</i> , 2019 , 19, 7254-7260 | 4 | 4 |
| 109 | . <i>IEEE Sensors Journal</i> , 2019 , 19, 11007-11013 | 4 | 4 |
| 108 | Sensitivity Improvement of MEMS Thermal Wind Sensor Using Vertical Stacking Thermistors 2019 , | | 4 |
| 107 | Modelling and characterization of a robust, low-power and wide-range thermal wind sensor. <i>Microsystem Technologies</i> , 2017 , 23, 5571-5585 | 1.7 | 4 |
| 106 | Large scale three-dimensional simulations for thick SU-8 lithography process based on a full hash fast marching method. <i>Microelectronic Engineering</i> , 2014 , 123, 171-174 | 2.5 | 4 |
| 105 | Temperature sensing properties of the passive wireless sensor based on graphene oxide films 2014 , | | 4 |
| 104 | Modeling of silicon thermal expansion using strained phonon spectra. <i>Journal of Micromechanics and Microengineering</i> , 2012 , 22, 085007 | 2 | 4 |
| 103 | Strain Effect of the Dielectric Constant in Silicon Dioxide. <i>Journal of Microelectromechanical Systems</i> , 2010 , 19, 1521-1523 | 2.5 | 4 |

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| 102 | A 3D profile simulator for inclined/multi-directional UV lithography process of negative-tone thick photoresists 2009 , | | 4 |
| 101 | A nodal analysis model for the out-of-plane beamshape electrothermal microactuator. <i>Microsystem Technologies</i> , 2009 , 15, 217-225 | 1.7 | 4 |
| 100 | A Modified 3D fast marching simulation for thick photoresists lithography 2011 , | | 4 |
| 99 | Effect of (2 × 1) Surface Reconstruction on Elasticity of a Silicon Nano-Plate. <i>Chinese Physics Letters</i> , 2008 , 25, 1403-1406 | 1.8 | 4 |
| 98 | An interpretation of reverse current in metal/intrinsic diamond/semiconducting diamond junction diodes. <i>Applied Surface Science</i> , 2001 , 171, 57-62 | 6.7 | 4 |
| 97 | Passive Wireless Hermetic Environment Monitoring System for Spray Painting Workshop. <i>Sensors</i> , 2016 , 16, | 3.8 | 4 |
| 96 | . <i>IEEE Sensors Journal</i> , 2019 , 19, 304-310 | 4 | 4 |
| 95 | Low-Drift MEMS Thermal Wind Sensor With Symmetric Packaging Using Plastic Injection Molding Process. <i>IEEE Transactions on Instrumentation and Measurement</i> , 2021 , 70, 1-8 | 5.2 | 4 |
| 94 | Analysis and Compensation of Benchmark Drift of Micromachined Thermal Wind Sensor Caused by Packaging Asymmetry. <i>IEEE Transactions on Industrial Electronics</i> , 2021 , 1-1 | 8.9 | 4 |
| 93 | Encapsulation glue Effect of Encapsulation Glue on Micromachined Thermal Wind Sensor 2018 , 2, 1-3 | | 4 |
| 92 | Fabrication of a Piezoresistive Barometric Pressure Sensor by a Silicon-on-Nothing Technology. <i>Journal of Sensors</i> , 2019 , 2019, 1-10 | 2 | 3 |
| 91 | Modeling, Simulation, and Fabrication of a 2-D Anemometer Based on a Temperature-Balanced Mode. <i>IEEE Sensors Journal</i> , 2019 , 19, 4796-4803 | 4 | 3 |
| 90 | A Novel Measurement Method of Mechanical Properties for Individual Layers in Multilayered Thin Films. <i>Micromachines</i> , 2019 , 10, | 3.3 | 3 |
| 89 | H2O adsorption-induced curvature of a silicon nanocantilever based on a semi-continuum method. <i>Applied Surface Science</i> , 2013 , 282, 662-671 | 6.7 | 3 |
| 88 | Modeling of the Effect of Process Variations on a Micromachined Doubly-Clamped Beam. <i>Micromachines</i> , 2017 , 8, 81 | 3.3 | 3 |
| 87 | A self-packaged two-dimensional thermal wind sensor based on thermopiles for low cost applications. <i>Journal of Micromechanics and Microengineering</i> , 2014 , 24, 075008 | 2 | 3 |
| 86 | A novel capacitive temperature sensor for a lab-on-a-chip system 2014 , | | 3 |
| 85 | Hot-forming of micro glass cavities for MEMS wafer level hermetic packaging 2010 , | | 3 |

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| 84 | Wafer level packaging based on AU-AU bonding for a CMOS compatible thermal wind sensor 2011 , | | 3 |
| 83 | An online test structure for the thermal expansion coefficient of surface micromachined polysilicon beams by a pull-in approach. <i>Journal of Micromechanics and Microengineering</i> , 2012 , 22, 055017 | 2 | 3 |
| 82 | An interpretation of SiO ₂ -induced emission instability in silicon field emitter. <i>Applied Surface Science</i> , 1998 , 136, 36-40 | 6.7 | 3 |
| 81 | Theoretical study of electromechanical property in a p-type silicon nanoplate for mechanical sensors. <i>Chinese Physics B</i> , 2008 , 17, 4292-4299 | 1.2 | 3 |
| 80 | GaAs piezoelectric modulated resistors. <i>Sensors and Actuators A: Physical</i> , 1993 , 35, 247-254 | 3.9 | 3 |
| 79 | A novel bonding technology for GaAs sensors. <i>Sensors and Actuators A: Physical</i> , 1990 , 21, 40-42 | 3.9 | 3 |
| 78 | Differential piezoresistive wind speed sensor on flexible substrate. <i>Electronics Letters</i> , 2020 , 56, 201-203 | 1.1 | 3 |
| 77 | Modeling of Packaged MEMS Thermal Wind Sensor Operating on CP Mode. <i>IEEE Transactions on Electron Devices</i> , 2019 , 66, 2375-2381 | 2.9 | 2 |
| 76 | Development of a robust 2-D thermal wind sensor using glass reflow process for low power applications 2015 , | | 2 |
| 75 | Effects of thermally induced packaging stress on a distributed RF MEMS phase shifter. <i>Microsystem Technologies</i> , 2015 , 21, 869-874 | 1.7 | 2 |
| 74 | Quadruple sensitivity improvement for wind speed sensor using dual-layer bended inductors. <i>Sensors and Actuators A: Physical</i> , 2020 , 303, 111786 | 3.9 | 2 |
| 73 | MEMS-Based Intraoperative Monitoring System for Improved Safety in Lumbar Surgery. <i>IEEE Sensors Journal</i> , 2013 , 13, 1541-1548 | 4 | 2 |
| 72 | Fabrication of a push-pull type electrostatic comb-drive RF MEMS switch 2012 , | | 2 |
| 71 | In situ test structures for the thermal expansion coefficient and residual stress of polysilicon thin films. <i>Journal of Micromechanics and Microengineering</i> , 2013 , 23, 075019 | 2 | 2 |
| 70 | A hybrid model for the charging process of the amorphous SiO ₂ film in radio frequency microelectromechanical system capacitive switches. <i>Chinese Physics B</i> , 2011 , 20, 037701 | 1.2 | 2 |
| 69 | Micro-rotating structures for determining thermal expansion coefficients of polysilicon thin films 2012 , | | 2 |
| 68 | An atomic level model for silicon anisotropic etching processes: Cellular automaton simulation and experimental verification. <i>Applied Physics Letters</i> , 2007 , 91, 174101 | 3.4 | 2 |
| 67 | On-line extraction for thermal conductivity of surface-micromachined polysilicon thin films | | 2 |

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| 66 | Design and 3D modeling investigation of a microfluidic electrode array for electrical impedance measurement of single yeast cells. <i>Electrophoresis</i> , 2021 , 42, 1996-2009 | 3.6 | 2 |
| 65 | Parallel capacitive temperature micro-sensor for passive wireless sensing applications. <i>Electronics Letters</i> , 2016 , 52, 1345-1347 | 1.1 | 2 |
| 64 | Experiments and Solution of Asymmetry Effect for Mems Thermal wind Sensor 2019 , | | 2 |
| 63 | Flexible Passive Wireless Pressure and Moisture Dual-Parameter Sensor for Wound Monitoring 2018 , | | 2 |
| 62 | Sensitivity Analysis of Micromachined Thermal Wind Sensor Based on Back Surface Sensing Mode 2018 , | | 2 |
| 61 | A self-packaged self-heated thermal wind sensor with high reliability and low power consumption 2015 , | | 1 |
| 60 | Influence of Aerodynamic Housing on the Performance of MEMS Wind Sensor 2020 , | | 1 |
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